



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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EZ18E01S  
(ON 0NIMVH)台裏図

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	10.Mar.2004	054585	DELETE ITEMS		H.TAKAHASHI	Y.YAHIRO	S.KASHIWAGI
3	24.May.2005	057352	DEVELOPMENT 80 CONTACTS		R.KATOU	M. Kimura	H. Otsuwa

DESIGNATION

命名法

KX15-\*\*\*KLD\*LE

シリーズ  
SERIES PREFIX

14:レセプタクル  
15:プラグ  
14:RECEPTACLE  
15:PLUG

芯数  
NO. OF CONTACTS

N:逆挿入防止キイ無  
K:逆挿入防止キイ有  
N:WITHOUT MISMATING PREVENTION KEY  
K:WITH MISMATING PREVENTION KEY

錫または錫合金(無鉛)  
(LEAD FREE)TIN/TIN ALLOY  
インシュレータ材料LCP品  
MATERIAL OF INSULATOR IS LCP

コンタクト仕上(表2参照)  
CONTACT FINISH (TABLE 2)

マウント形状

D:位置決めボス有、ホールドダウン付  
F:位置決めボス無、ホールドダウン付

MOUNT:

D:WITH POSITIONING BOSS, WITH HOLD-DOWN  
F:WITHOUT POSITIONING BOSS, WITH HOLD-DOWN

アングルタイプ  
RIGHT ANGLE TYPE

TABLE 1 DIMENSION

芯数 NO. OF CONTACT	A	B	C	D
20	7.2	8.7	10.3	16
30	11.2	12.7	14.3	20
40	15.2	16.7	18.3	24
50	19.2	20.7	22.3	28
60	23.2	24.7	26.3	32
70	27.2	28.7	30.3	36
△ 80	31.2	32.7	34.3	40

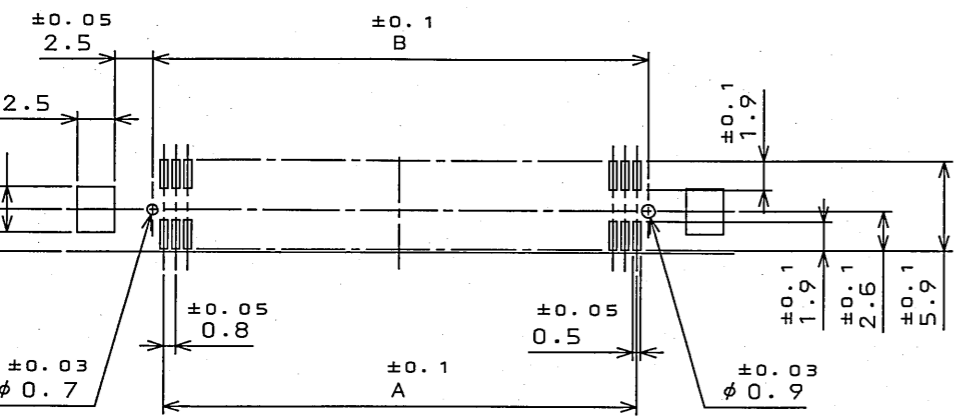
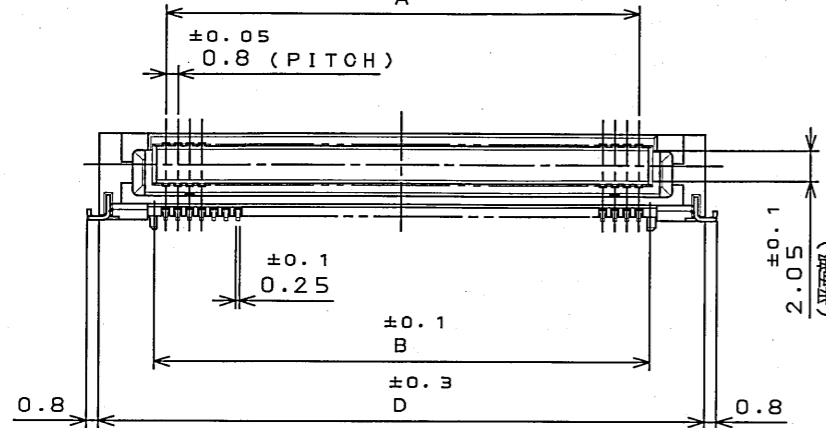
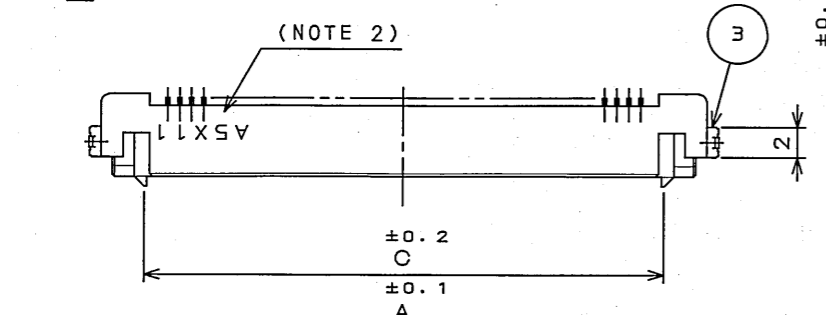
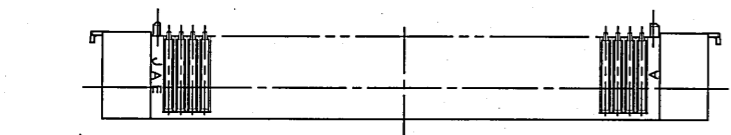
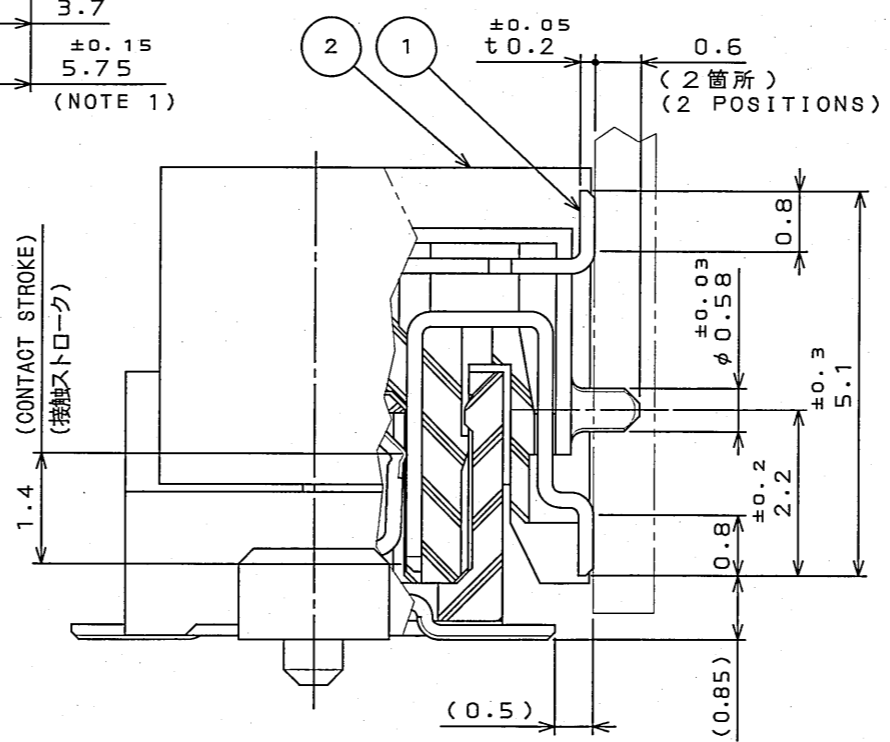
TABLE 2 FINISH

表2 仕上

FINISH 仕上記号	CONTACT AREA 接触部仕上	TERMINAL AREA 端子部仕上
NONE 無印	GOLD PLATING OVER NICKEL (GOLD:0.1μmMIN) Ni上Au0.1μm以上	GOLD FLASH OVER NICKEL Ni上Auフラッシュ

MATED CONDITION (REF.) (SCALE 10:1)

嵌合状態図(参考)(尺度10:1)



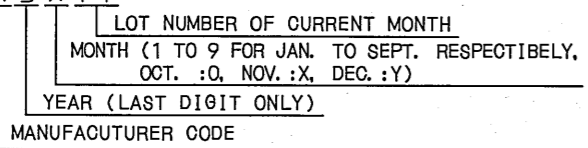
APPLICABLE P.C.B. DIMENSION (REF.)

適合基板寸法(参考)

NOTE 1. COPLANARITY: 0.1mm MAX.

2. PRODUCTION LOT NUMBER AS INDICATED.

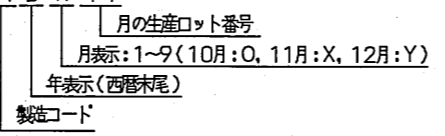
(EX.) A5X11



注 1. 端子の平坦度は、0.1以下。

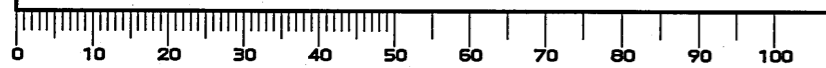
2. 図示の面に、ロット番号を表示する。

(例) A5X11



3	HOLD DOWN	2	COPPER ALLOY	(LEAD FREE)TIN/TIN ALLOY	
2	INSULATOR	1	GLASS FILLED LCP		COLOR : BLACK
1	CONTACT	TABLE 1	COPPER ALLOY	TABLE 2	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材 料 MATERIAL	仕 上 FINISH	備 考 REMARKS
仕様書(SPECIFICATION)		第1版(ORIGINAL DATE)		尺度(SCALE)	シリーズ(SERIES)
JAcs-1401-		3.Mar.2003		2:1	KX
製図 DR.		M.TANAKA		名称(TITLE)	
担当 CHK.		H.TAKAHASHI		KX15-***KLD*LE	
査閲 APPD.					
承認 APPD.		S.KASHIWAGI		質量(MASS)	
日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.					図面番号(DRAWING NO.)
					SJ038123
					版数 (REV.)
					3

DOF-0-212E(03.08)



LEAD FREE この製品は鉛フリー品です